MG031E120004A

3 phase Inverter Module

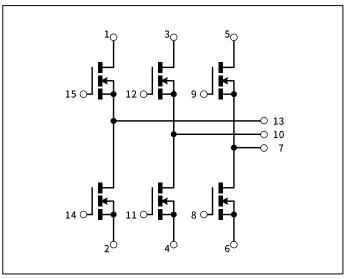
Feature

- 3 phase Inverter
- MOSFET(N-channel)
- High current capacity
- Low Ron
- Halogen free
- Pb free terminal
- RoHS:Yes

Outline



Equivalent circuit



MOSFET

ltem	Symbol	Conditions	Ratings	Unit
Channel temperature	Tch		175	°C
Drain-source voltage	V _{DSS}		40	v
Gate-source voltage	V _{GSS}		±20	v
Continuous drain current (DC)	I _D		120	А
Continuous drain current (Peak)	I _{DP}	Pulse width 10µs, Duty = 1/10	480	А
Total power dissipation	P _T		125	w
Single avalanche current	I _{AS}	Starting Tch=25°C Tch≦150°C	40	А
Single avalanche energy	E _{AS}	Starting Tch=25°C Tch≦150°C	185	mJ

Module

ltem	Symbol	Conditions	Ratings	Unit
Storage temperature	Tstg		-55~150	°C
Mounting torque	TOR	Fixing screw M3	0.8	N∙m

Ratings Symbol Conditions Unit Item Min. Typ. Max. I_D=1mA, V_{GS}=0V 40 v V_{(BR)DSS} _ Drain-source breakdown voltage V_{DS}=40V, V_{GS}=0V 1.0 μΑ I_{DSS} _ _ Zero gate voltage drain current $V_{GS}=\pm 20V, V_{DS}=0V$ I_{GSS} ±0.1 μΑ _ _ Gate-source leakage current Chip I_D=60A, V_{GS}=10V 1.89 _ mΩ _ Static drain-source on-state R_{DS(ON)} resistance Terminal I_D=60A, V_{GS}=10V 2.4 3.1 mΩ _ I_D=1mA, V_{DS}=10V 2.0 3.0 4.0 v VTH Gate threshold voltage Source-drain diode forward V_{SD} Is=120A, V_{GS}=0V _ _ 1.5 ٧ voltage Qg _ 61 ____ Total gate charge V_{DD} =32V, V_{GS} =10V, I_{D} =120A Qgs _ 17.5 nC Gate to source charge (Electrical characteristics of discrete MOSFET device) Qgd _ 23 Gate to drain charge Ciss _ 3297 _ Input capacitance V_{DS}=25V, V_{GS}=0V, f=1MHz Crss _ 254 _ рF Reverse transfer capacitance (Electrical characteristics of discrete MOSFET device) Coss 536 Output capacitance td(on) 10 Turn-on delay time ID=60A, VDD=20V, RL=0.33Ω, Rg=0Ω, tr 82 **Rise time** VGS(+)=10V, VGS(-)=0V ns td(off) (Electrical characteristics of discrete MOSFET device) 28 Turn-off delay time tf 10 _ **Fall time** Source-drain diode reverse _ _ 32 trr ns recovery time IF=120A, VGS=0V, di/dt=100A/µs Source-drain diode reverse Qrr 38 nC recovery charge

MOSFET

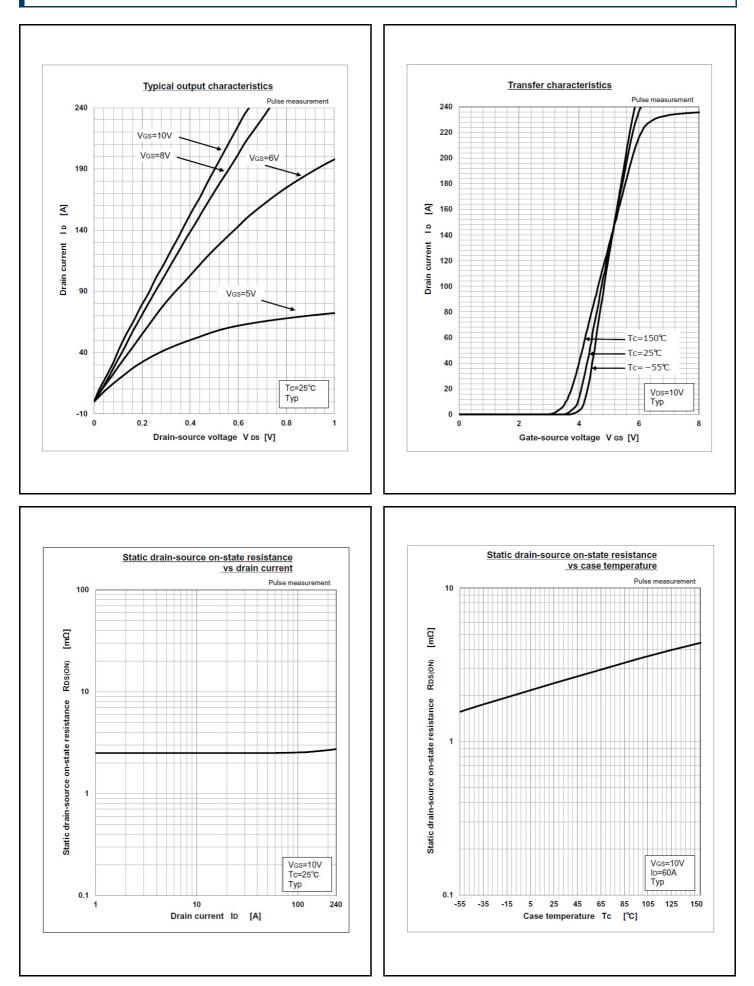
These are characteristics of the 1 chip unless otherwise specified.

Module

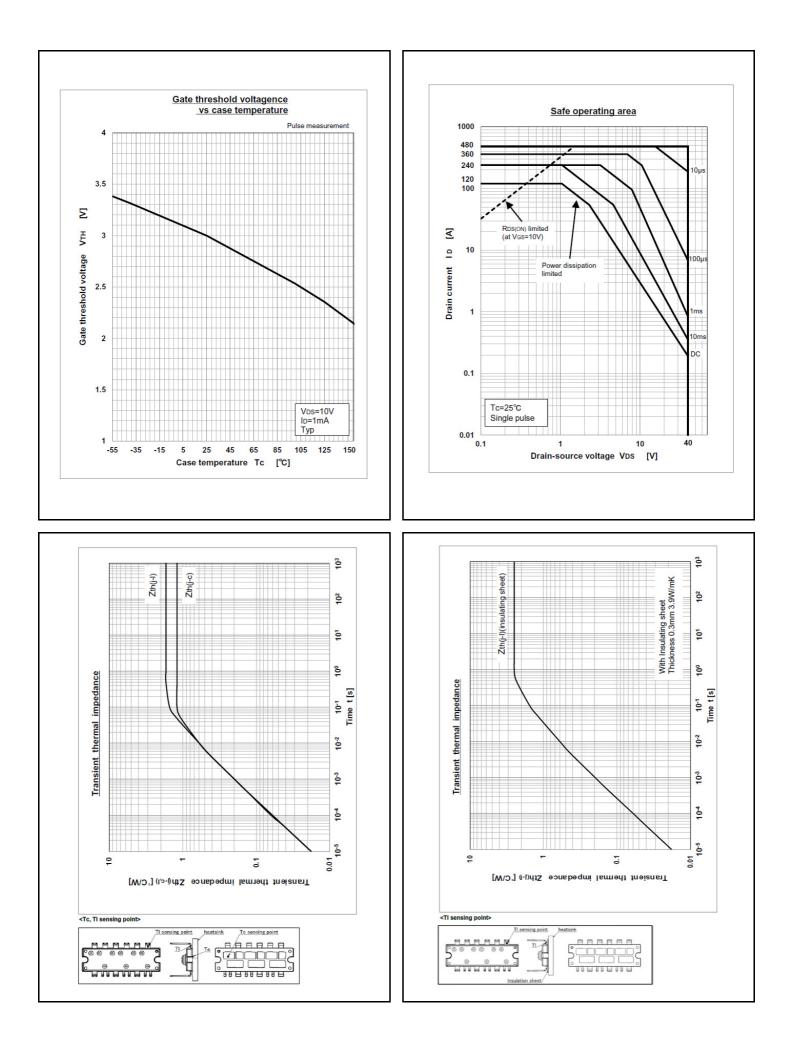
ltem	Symbol	Conditions	Ratings			Unit
			Min.	Тур.	Max.	
Thermal resistance	R _{th(j-c)}	Junction to case	Ι	-	1.2	
		Junction to lead	-	_	1.7	
	R _{th(j-l)}	Junction to lead, With insulating sheet, Thickness 0.3mm, Thermal conductivity 3.9W/mK	_	_	2.5	°C/W

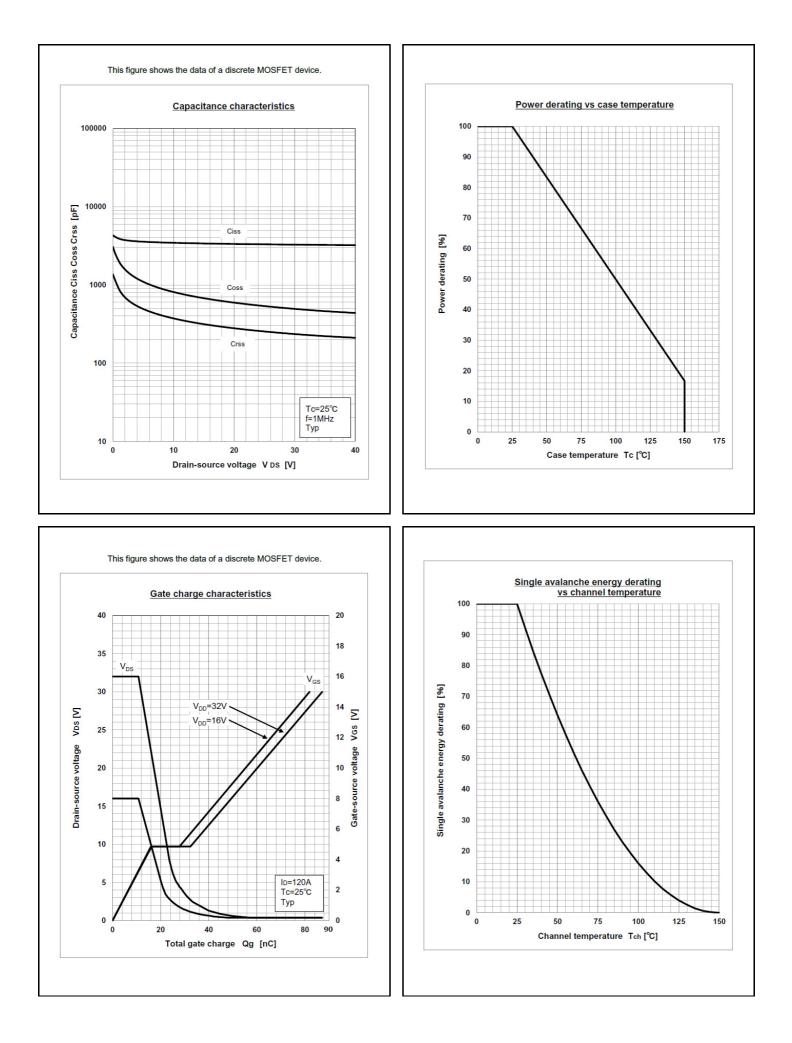
Note: Thermal resistance was measured at Q3

CHARACTERISTIC DIAGRAMS



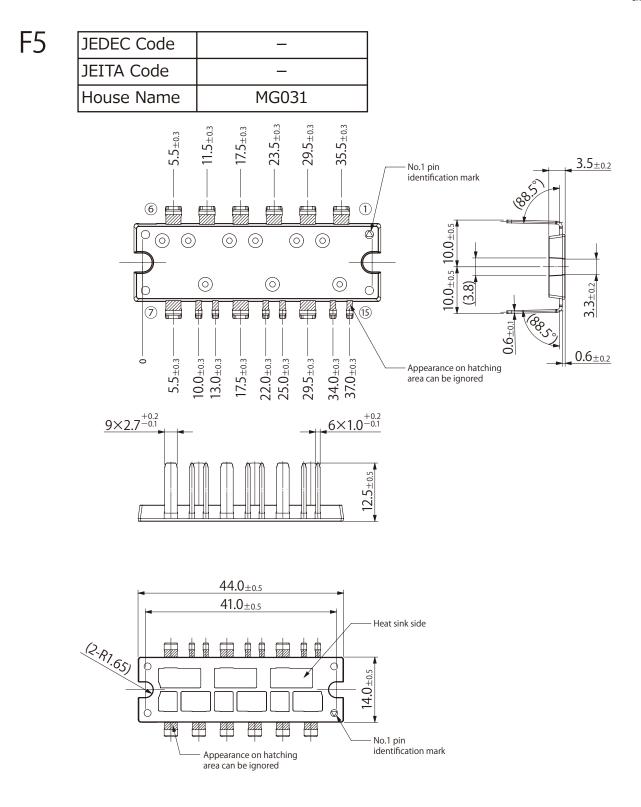
Shindengen Electric Manufacturing Co., Ltd.





Package Outline-Dimensions

unit:mm



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